



Certificate of Non-use for The Controlled Substances / 不使用禁用物質證明書
(For approval/承認用)

Date/日期: 2014.08.29

Customer name/客戶公司名稱: SEMISOLUTION INC.

Company name/公司名稱: Faraday Technology Corporation

E-mail/電子郵件: rohs@faraday-tech.com

Responsible-person name/負責人姓名: Jessie Liao

Jessie Liao



Faraday Product No./智原產品料號: FSA0AC149BC

Customer Product No./客戶產品料號: W5100

We hereby declare this "Product" that all substances of combinations meet RoHS requirement. Regarding the above-mentioned materials and substances, we notify that they are composed of the ingredients given at the composition table.

我們公司在此宣告此「產品」之所有組成物質，符合歐盟所訂定之禁用物質管理標準。關於上述提及的材質與組成物質，我們將在成分表中完整告知產品之所有組成成份。

Applied for/適用於:

RoHS requirement Level 5: Exemptions/歐盟所明列之禁用物質排除條款

Substances Prohibited as per RoHS requirement/歐盟所明列之禁用物質

Substance	Maximum Concentration Value
Cadmiun (Cd)	< 0.01% = < 100ppm
Lead (Pb)	< 0.10% = < 1,000 ppm
Mercury (Hg)	< 0.10% = < 1,000 ppm
Hexavalent Chromium (Cr6+)	< 0.10% = < 1,000 ppm
Poly Brominated Biphenyls (PBB)	< 0.10% = < 1,000 ppm
Poly Brominated Diphenyl Ethers (PBDE)	< 0.10% = < 1,000 ppm



<Substances Prohibited as per RoHS requirement/歐盟所明列之禁用物質>

1. Heavy metals/重金屬
 - a. Cadmium and cadmium compounds/鎘以及鎘化合物
 - b. Lead and lead compounds/鉛以及鉛化合物
 - c. Mercury and mercury compounds/汞以及汞化合物
 - d. Hexavalent chromium compounds/六價鉻化合物
 - e. Nickel and Nickel compounds/鎳以及鎳化合物
2. Brominated organic compounds/有機溴化合物
 - a. Polybrominated biphenyls (PBB)/多溴聯苯
 - b. Polybrominated diphenylethers (PBDE)/多溴二苯醚
 - c. Other brominated organic compounds/其他有機溴化合物
3. Chlorinated organic compounds/有機氯化合物
 - a. Polychlorinated biphenyls (PCB)/多氯聯苯
 - b. Polychlorinated naphthalenes (PCN)/多氯化萘
 - c. Polychlorinated terphenyls (PCT)/聚氯三聯苯
 - d. Chlorinated paraffins (CP)/氯化烷烴
 - e. Other chlorinated organic compounds/其他有機氯化合物
4. Tributyl tin compound, Triphenyl tin compounds/三丁基錫化合物、三苯基錫化合物
5. Asbestos/石棉
6. Specific Azo compounds/特定偶氮化合物
7. Formaldehyde/甲醛
8. Polyvinyl chloride (PVC) and PVC blends/聚氯乙烯以及聚氯乙烯混合物

<RoHS requirement Level 5: Exemptions/歐盟所明列之禁用物質排除條款>

1. Mercury in compact fluorescent lamps not exceeding 5 mg per lamp.
2. Mercury in straight fluorescent lamps for general purposes not exceeding:
 - halophosphate 10 mg
 - triphosphate with normal lifetime 5 mg
 - triphosphate with long lifetime 8 mg.
3. Mercury in straight fluorescent lamps for special purposes.
4. Mercury in other lamps not specifically mentioned in this Annex.
5. Lead in glass of cathode ray tubes, electronic components and fluorescent tubes.
6. Lead as an alloying element in steel containing up to 0.35 % lead by weight, aluminum containing up to 0.4 % lead by weight and as a copper alloy containing up to 4 % lead by weight.
7. — Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead),



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- lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission as well as network management for telecommunications,
 - lead in electronic ceramic parts (e.g. piezoelectronic devices);
8. Cadmium and its compounds in electrical contacts and cadmium plating except for applications banned under Directive 91/338/EEC (*) amending Directive 76/769/EEC (**) relating to restrictions on the marketing and use of certain dangerous substances and preparations.
 9. Hexavalent chromium as an anti-corrosion of the carbon steel cooling system in absorption refrigerators.
 - 9a. Deca BDE in polymeric applications;
 - 9b. Lead in lead-bronze bearing shells and bushes
 10. Within the procedure referred to in Article 7(2), the Commission shall evaluate the applications for:
 - Deca BDE,
 - mercury in straight fluorescent lamps for special purposes,
 - lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signalling, transmission as well as network management for telecommunications (with a view to setting a specific time limit for this exemption), and
 - light bulbs,as a matter of priority in order to establish as soon as possible whether these items are to be amended accordingly.
 11. Lead used in compliant pin connector systems.
 12. Lead as a coating material for the thermal conduction module c-ring.
 13. Lead and cadmium in optical and filter glass.
 14. Lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 80 % and less than 85 % by weight.
 15. Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages.

*If any required items cannot be written on this above sheet, write necessary items on the below remark.

如有任何重要事項未能填寫在此上述表單，請書寫在註記欄位中。

Remarks/註記: